



## STV9379FA

### VERTICAL DEFLECTION BOOSTER

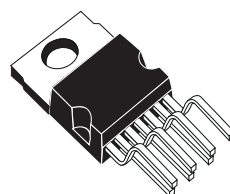
- POWER AMPLIFIER
- THERMAL PROTECTION
- OUTPUT CURRENT UP TO 2.6A<sub>PP</sub>
- FLYBACK VOLTAGE UP TO 90V (on Pin 5)
- SUITABLE FOR DC COUPLING APPLICATION
- EXTERNAL FLYBACK SUPPLY

#### DESCRIPTION

Designed for monitors and high performance TVs, the STV9379FA vertical deflection booster can handle flyback voltage up to 90V. Further to this, it is possible to have a flyback voltage which is more than the double of the supply (Pin 2). This allows to decrease the power consumption, or to decrease the flyback time for a given supply voltage.

The STV9379FA operates with supplies up to 42V and provides up to 2.6A<sub>PP</sub> output current to drive the yoke.

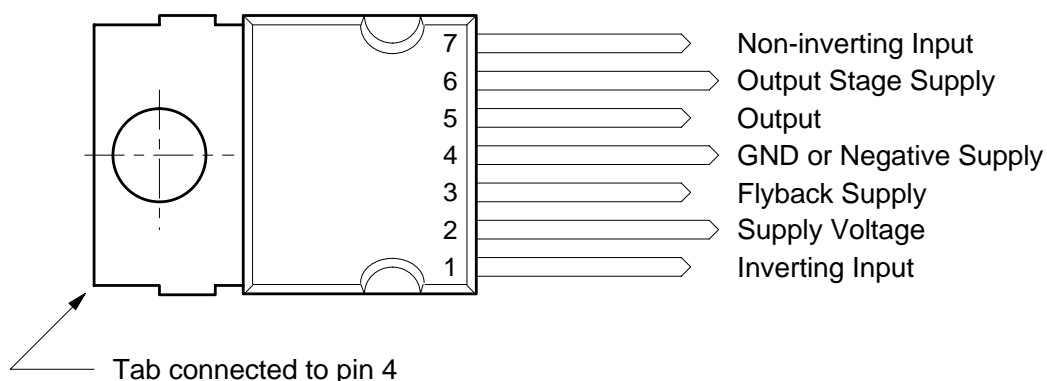
The STV9379FA is offered in HEPTAWATT package.



**HEPTAWATT**  
(Plastic Package)

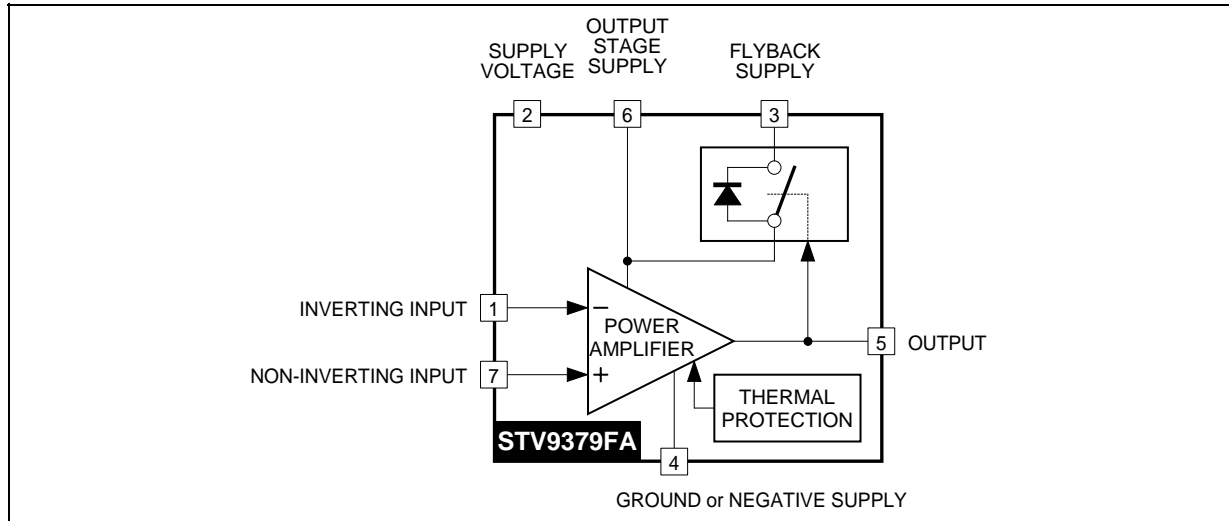
**ORDER CODE : STV9379FA**

#### PIN CONNECTIONS



9379FA01.EPS

## BLOCK DIAGRAM



## ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
$V_S$	Supply Voltage (Pin 2) (see note 1)	50	V
$V_6$	Flyback Peak Voltage (Pin 6) (see note 1)	100	V
$V_1, V_7$	Amplifier Input Voltage (Pins 1-7) (see note 1)	- 0.3, + $V_S$	V
$I_O$	Maximum Output Peak Current (see notes 2 and 3)	1.8	A
$I_3$	Maximum Sink Current ( $t < 1\text{ms}$ )	1.8	A
$I_3$	Maximum Source Current ( $t < 1\text{ms}$ ) (in the diode, see Block Diagram) (see note 2)	1.8	A
$V_{ESD}$	ESD susceptibility : EIAJ Norm (200pF discharged through 0Ω)	300	V
$V_3 - V_2$	Voltage Difference between Flyback Supply and Supply Voltage	50	V
$T_{oper}$	Operating Ambient Temperature	- 20, + 75	°C
$T_{stg}$	Storage Temperature	- 40, + 150	°C
$T_j$	Junction Temperature	+150	°C

- Notes :**
1. Versus Pin 4.
  2. The output current can reach 5A peak for  $t \leq 10\mu\text{s}$  (up to 120Hz).
  3. Provided SOAR is respected (see Figures 1 and 2).

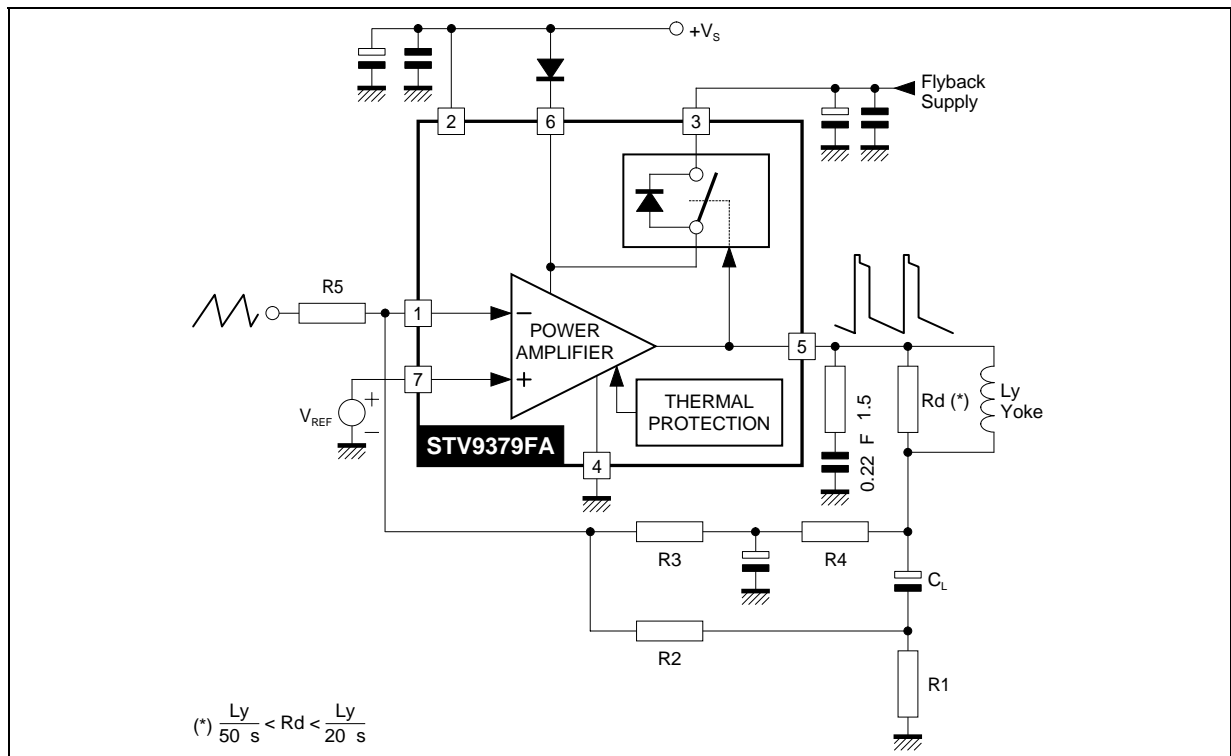
## THERMAL DATA

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction-case Thermal Resistance Max.	3	°C/W
$T_t$	Temperature for Thermal Shutdown	150	°C
$\Delta T_t$	Hysteresis on $T_t$	10	°C
$T_{jr}$	Recommended Max. Junction Temperature	120	°C

**ELECTRICAL CHARACTERISTICS**(V<sub>S</sub> = 42V, T<sub>A</sub> = 25°C, unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>S</sub>	Operating Supply Voltage Range	Versus Pin 4	10		42	V
V <sub>3M</sub>	Operating Flyback Supply Voltage (V <sub>3M</sub> ≤ V <sub>S</sub> + 50V)	Versus Pin 4	V <sub>S</sub>		90	V
I <sub>2</sub>	Pin 2 Quiescent Current	I <sub>3</sub> = 0, I <sub>5</sub> = 0		13	20	mA
I <sub>6</sub>	Pin 6 Quiescent Current	I <sub>3</sub> = 0, I <sub>5</sub> = 0	5	10	30	mA
I <sub>O</sub>	Max. Operating Peak Output Current				1.3	A
I <sub>1</sub>	Amplifier Bias Current	V <sub>1</sub> = 22V, V <sub>7</sub> = 23V		- 0.15	- 1	μA
I <sub>7</sub>	Amplifier Bias Current	V <sub>1</sub> = 23V, V <sub>7</sub> = 22V		- 0.15	- 1	μA
V <sub>IO</sub>	Offset Voltage				7	mV
ΔV <sub>IO</sub> /dt	Offset Drift versus Temperature			- 10		μV/°C
GV	Voltage Gain		80			dB
V <sub>5L</sub>	Output Saturation Voltage to GND (Pin 4)	I <sub>5</sub> = 1.3A		1	1.6	V
V <sub>5H</sub>	Output Saturation Voltage to Supply (Pin 6)	I <sub>5</sub> = - 1.3A		1.6	2.2	V
V <sub>D5-6</sub>	Diode Forward Voltage between Pins 5-6	I <sub>5</sub> = 1.3A		1.4	2.1	V
V <sub>D3-6</sub>	Diode Forward Voltage between Pins 3-6	I <sub>3</sub> = 1.3A		1.7	2.5	V
V <sub>3-6</sub>	Voltage Drop between Pins 3-6 (2nd part of flyback)	I <sub>3</sub> = - 1.3A		2.9	3.6	V

9379FA03.TBL

**APPLICATION CIRCUITS****AC COUPLING**

9379FA03.EPS

APPLICATION CIRCUITS (continued)  
DC COUPLING

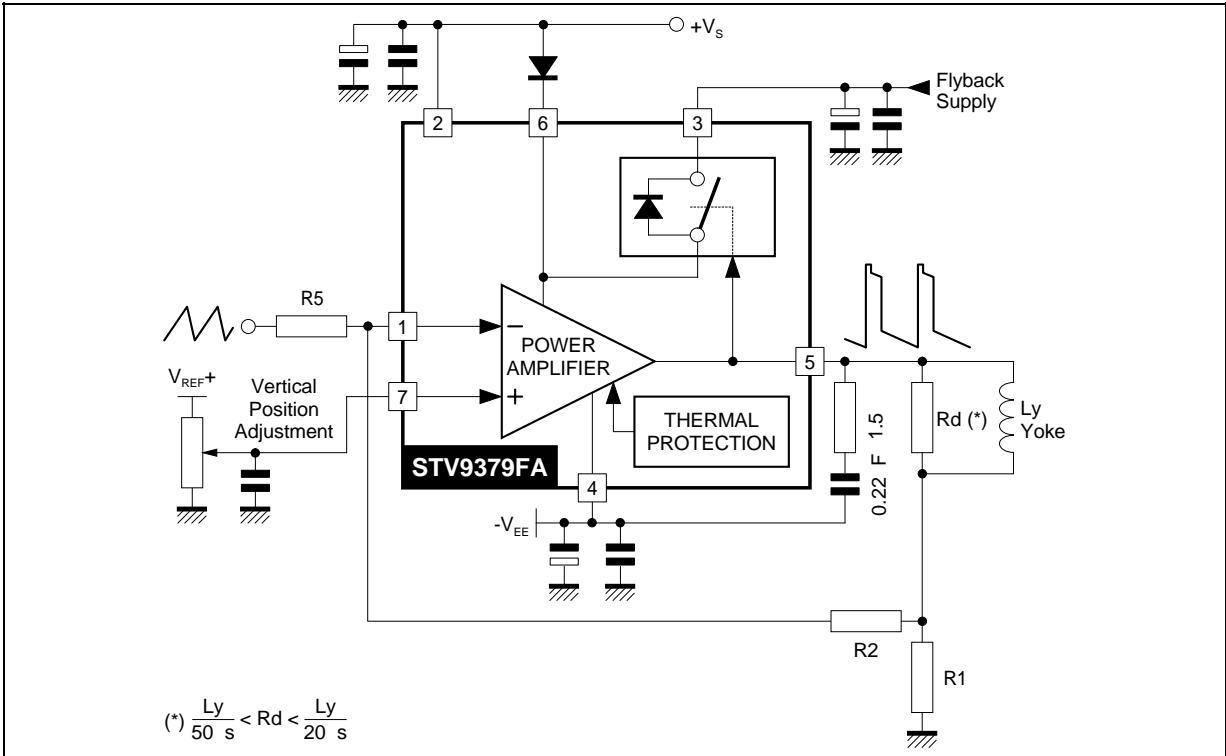


Figure 1 : Output Transistors SOA  
(for secondary breakdown)

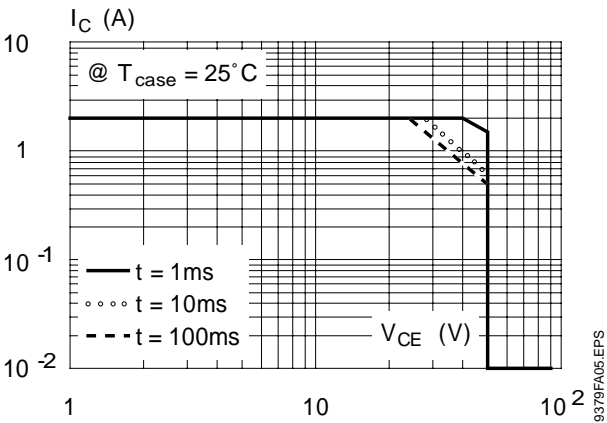
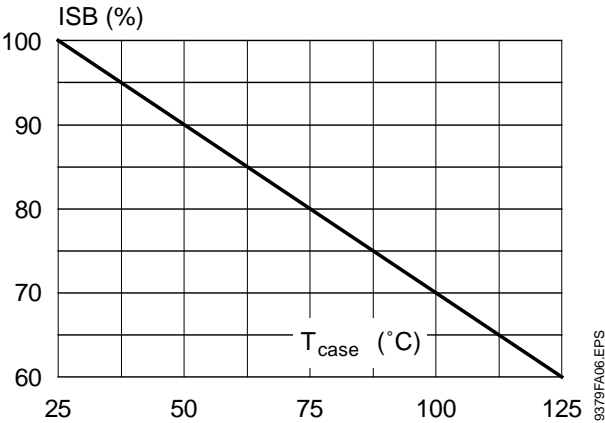
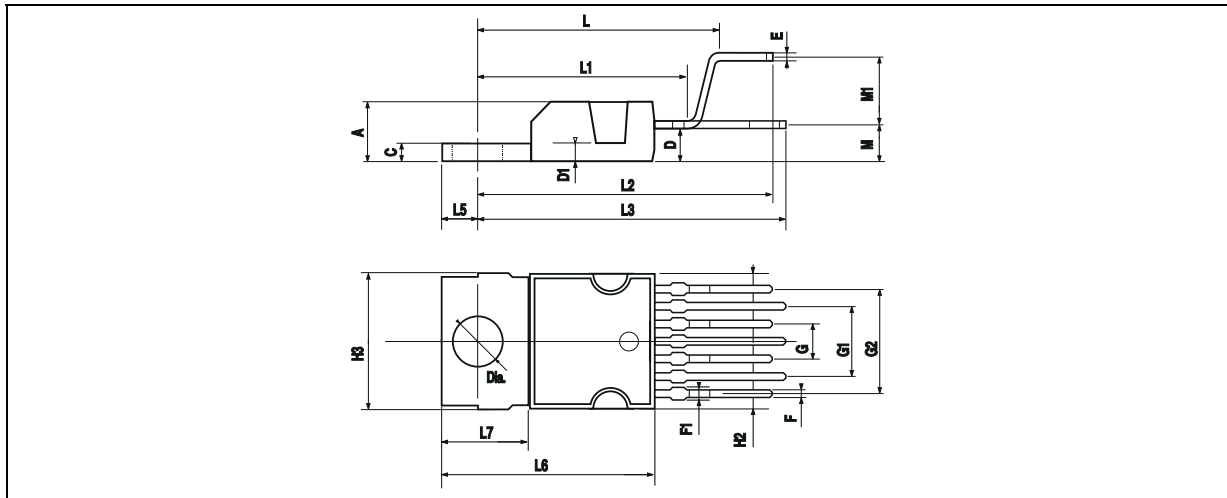


Figure 2 : Secondary Breakdown Temperature  
Derating Curve  
(ISB = secondary breakdown current)



## PACKAGE MECHANICAL DATA : 7 PINS - PLASTIC HEPTAWATT



PM-HEPTV/EP5

Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			4.8			0.189
C			1.37			0.054
D	2.4		2.8	0.094		0.110
D1	1.2		1.35	0.047		0.053
E	0.35		0.55	0.014		0.022
F	0.6		0.8	0.024		0.031
F1			0.9			0.035
G	2.41	2.54	2.67	0.095	0.100	0.105
G1	4.91	5.08	5.21	0.193	0.200	0.205
G2	7.49	7.62	7.8	0.295	0.300	0.307
H2			10.4			0.409
H3	10.05		10.4	0.396		0.409
L		16.97			0.668	
L1		14.92			0.587	
L2		21.54			0.848	
L3		22.62			0.891	
L5	2.6		3	0.102		0.118
L6	15.1		15.8	0.594		0.622
L7	6		6.6	0.236		0.260
M		2.8			0.110	
M1		5.08			0.200	
Dia.	3.65		3.85	0.144		0.152

HEPTV/TBL

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